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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HD74AC259

8-bit Addressable Latch



ADE-205-385 (Z)

1st. Edition

Sep. 2000

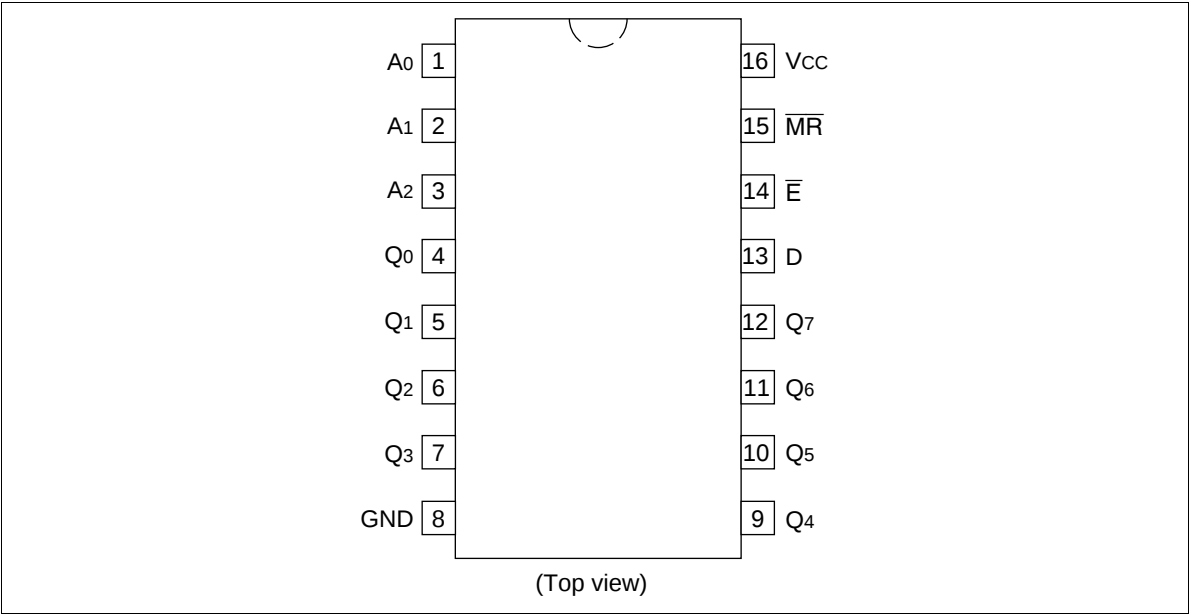
Description

The HD74AC259 is a high-speed 8-bit addressable latch designed for general purpose storage applications in digital systems. It is a multifunctional device capable of storing single line data in eight addressable latches, and also a 1-of-8 decoder and demultiplexer with active HIGH outputs. The device also incorporates an active LOW Common Clear for resetting all latches, as well as an active LOW Enable.

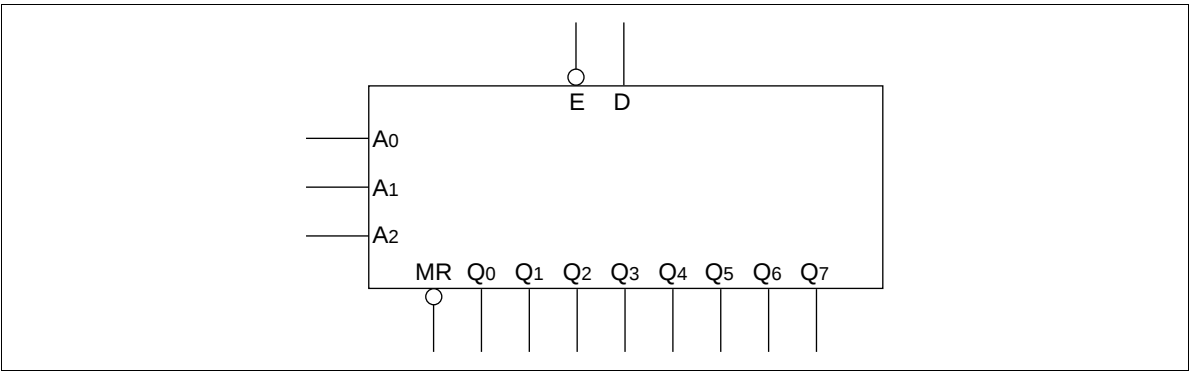
Features

- Serial-to-Parallel Conversion
- Eight Bits of Storage with Output of Each Bit Available
- Random (Addressable) Data Entry
- Active High Demultiplexing or Decoding Capability
- Easily Expandable
- Common Clear
- Outputs Source/Sink 24 mA

Pin Arrangement



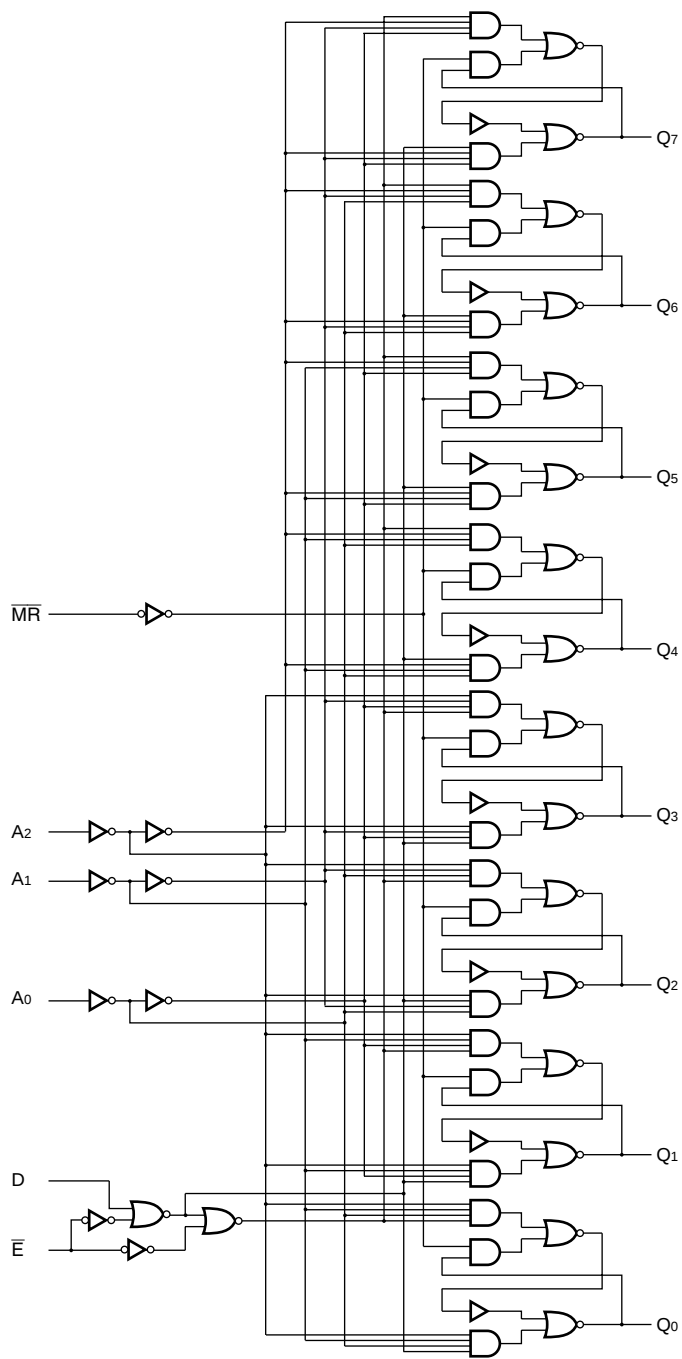
Logic Symbol



Pin Names

- $A_0 - A_2$ Address Inputs
- D Data Inputs
- $\overline{E}$ Enable Input (Active LOW)
- $\overline{MR}$ Master Reset (Active LOW)
- $Q_0 - Q_7$ Latch Outputs

Logic Diagram



Function Table

Operating Mode	Inputs						Outputs							
	$\overline{MR}$	$\overline{E}$	D	A ₀	A ₁	A ₂	Q ₀	Q ₁	Q ₂	Q ₃	Q ₄	Q ₅	Q ₆	Q ₇
Master reset	L	H	X	X	X	X	L	L	L	L	L	L	L	L
Demultiplex	L	L	d	L	L	L	Q = d	L	L	L	L	L	L	L
(Active HIGH	L	L	d	H	L	L	L	Q = d	L	L	L	L	L	L
Decoder when	L	L	d	L	H	L	L	L	Q = d	L	L	L	L	L
D = H)	L	L	d	H	H	L	L	L	L	Q = d	L	L	L	L
	L	L	d	L	L	H	L	L	L	L	Q = d	L	L	L
	L	L	d	H	L	H	L	L	L	L	L	Q = d	L	L
	L	L	d	L	H	H	L	L	L	L	L	L	Q = d	L
	L	L	d	H	H	H	L	L	L	L	L	L	L	Q = d
Store (Do nothing)	H	H	X	X	X	X	q ₀	q ₁	q ₂	q ₃	q ₄	q ₅	q ₆	q ₇
Addressable latch	H	L	d	L	L	L	Q = d	q ₁	q ₂	q ₃	q ₄	q ₅	q ₆	q ₇
	H	L	d	H	L	L	q ₀	Q = d	q ₂	q ₃	q ₄	q ₅	q ₆	q ₇
	H	L	d	L	H	L	q ₀	q ₁	Q = d	q ₃	q ₄	q ₅	q ₆	q ₇
	H	L	d	H	H	L	q ₀	q ₁	q ₂	Q = d	q ₄	q ₅	q ₆	q ₇
	H	L	d	L	L	H	q ₀	q ₁	q ₂	q ₃	Q = d	q ₅	q ₆	q ₇
	H	L	d	H	L	H	q ₀	q ₁	q ₂	q ₃	q ₄	Q = d	q ₆	q ₇
	H	L	d	L	H	H	q ₀	q ₁	q ₂	q ₃	q ₄	q ₅	Q = d	q ₇
	H	L	d	H	H	H	q ₀	q ₁	q ₂	q ₃	q ₄	q ₅	q ₆	Q = d

H : High Voltage Level

L : Low Voltage Level

X : Immaterial

d : High or Low data one setup time prior to the Low-to-High Enable transition.

q : Lower case letters indicate the state of the referenced output established during the last cycle in which it was addressed or cleared.

DC Characteristics (unless otherwise specified)

Item	Symbol	Max	Unit	Condition
Maximum quiescent supply current	I _{CC}	80	μA	V _{IN} = V _{CC} or ground, V _{CC} = 5.5 V, Ta = Worst case
Maximum quiescent supply current	I _{CC}	8.0	μA	V _{IN} = V _{CC} or ground, V _{CC} = 5.5 V, Ta = 25°C

AC Characteristics: HD74AC259

Item	Symbol	V _{CC} (V)*1	Ta = +25°C C _L = 50 pF			Ta = -40°C to +85°C C _L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
Maximum clock frequency	f _{max}	3.3	65	—	—	60	—	MHz
		5.0	110	—	—	95	—	
Propagation delay MR to Q _n	t _{PHL}	3.3	1.0	8.5	14.5	1.0	16.5	ns
		5.0	1.0	6.5	9.0	1.0	10.5	
Propagation delay D _n to Q _n	t _{PLH}	3.3	1.0	7.0	10.5	1.0	12.0	ns
		5.0	1.0	5.5	7.5	1.0	8.5	
Propagation delay D _n to Q _n	t _{PHL}	3.3	1.0	7.0	10.5	1.0	12.0	ns
		5.0	1.0	5.5	7.5	1.0	8.5	
Propagaion delay A _n to Q _n	t _{PLH}	3.3	1.0	11.5	18.5	1.0	21.5	ns
		5.0	1.0	8.0	11.5	1.0	14.0	
Propagation delay A _n to Q _n	t _{PHL}	3.3	1.0	11.5	18.5	1.0	21.0	ns
		5.0	1.0	8.0	11.5	1.0	13.5	
Propagation delay E to Q	t _{PLH}	3.3	1.0	9.0	15.0	1.0	17.0	ns
		5.0	1.0	6.5	9.0	1.0	10.5	
Propagation delay E to Q _n	t _{PHL}	3.3	1.0	9.0	14.0	1.0	16.0	ns
		5.0	1.0	6.5	8.5	1.0	10.0	

Note: 1. Voltage Range 3.3 is 3.3 V ± 0.3 V
Voltage Range 5.0 is 5.0 V ± 0.5 V

HD74AC259

AC Operating Requirements: HD74AC259

			Ta = +25°C C _L = 50 pF	Ta = −40°C to +85°C C _L = 50 pF		
Item	Symbol	V _{CC} (V)*1	Typ	Guaranteed Minimum		Unit
Setup time, HIGH or LOW D to $\bar{E}$	t _{su}	3.3	1.0	3.5	3.5	ns
		5.0	0.0	3.0	3.0	
Hold time, HIGH or LOW D to $\bar{E}$	t _h	3.3	0.5	2.0	2.0	ns
		5.0	0.5	2.0	2.0	
Setup time, HIGH or LOW A _n to $\bar{E}$	t _{su}	3.3	1.0	6.0	7.0	ns
		5.0	0.0	4.5	5.0	
Hold time, HIGH or LOW A _n to $\bar{E}$	t _h	3.3	−3.0	0.0	0.0	ns
		5.0	−1.0	0.0	0.0	
Pulse width	t _w	3.3	3.0	5.5	7.0	ns
		5.0	3.0	4.5	5.0	

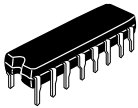
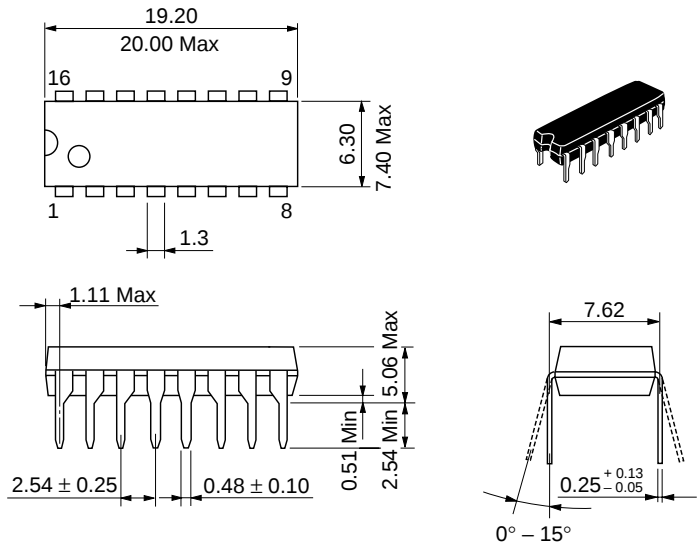
Note: 1. Voltage Range 3.3 is 3.3 V ± 0.3 V
Voltage Range 5.0 is 5.0 V ± 0.5 V

Capacitance

Item	Symbol	Typ	Unit	Condition
Input capacitance	C _{IN}	4.5	pF	V _{CC} = 5.5 V
Power dissipation capacitance	C _{PD}	35	pF	V _{CC} = 5.0 V

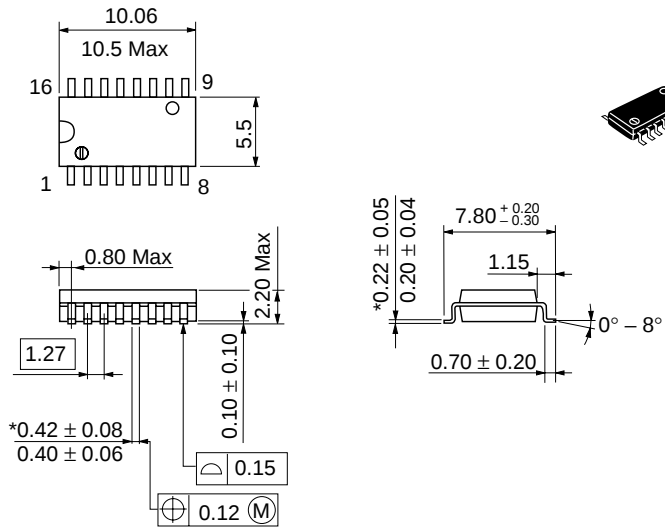
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

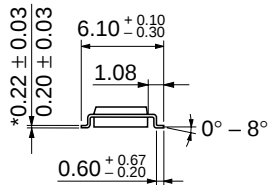
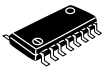
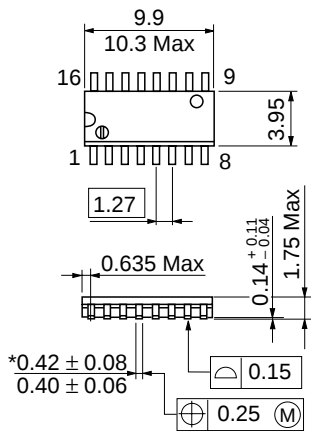
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

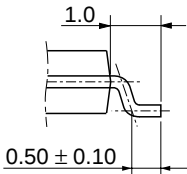
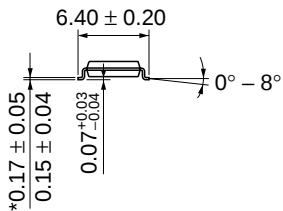
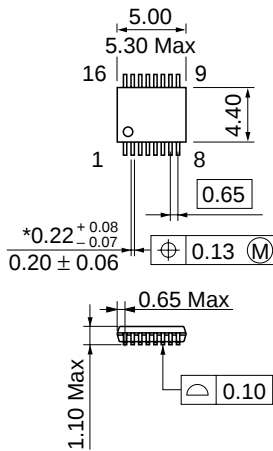
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.15 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	TTP-16DA
JEDEC	—
EIAJ	—
Mass (reference value)	0.05 g

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